



EIA/IPC/JEDEC J-STD-002D

Solderability Tests for Component Leads, Terminations, Lugs, Terminals and Wires

A joint standard developed by IPC Components and Wire Solderability Specification Task Group (5-23b) of the Assembly and Joining Processes Committee (5-20), the Electronic Components Industry Association Soldering Technology Committee (STC) and the JEDEC Solid State Technology Association Committee (JC14.1)

Users of this standard are encouraged to participate in the development of future revisions.

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Contact:

**EIA Standards
Electronic Components
Industry Association**

2214 Rock Hill Road, Suite 170
Herndon, VA 20170-4212
Phone: (571) 323-0294
Fax: (571) 323-0245

**JEDEC Solid State Technology
Association**

3103 North 10th Street, Suite 240-S
Arlington, VA 22201-2107
Phone: (703) 907-7540
Fax: (703) 907-7583

**IPC
Association Connecting
Electronics Industries®**

3000 Lakeside Drive, Suite 309S
Bannockburn, IL 60015-1249
Phone: (847) 615-7100
Fax: (847) 615-7105

Table of Contents

1	PREFACE	1	4.2.1	Test A - SnPb Solder – Solder Bath/Dip and Look Test (Leads, Wires, etc.)	7
1.1	Scope	1	4.2.2	Test B - SnPb Solder – Solder Bath/Dip and Look Test (Leadless Components)	9
1.2	Purpose	1	4.2.3	Test C - SnPb Solder – Wrapped Wires Test (Lugs, Tabs, Terminals, Large Stranded Wires)	10
1.2.1	Shall and Should	1	4.2.4	Test D - SnPb or Pb-free Solder – Resistance to Dissolution of Metallization Test	12
1.3	Method Classification	1	4.2.5	Test S - SnPb Solder – Surface Mount Process Simulation Test	13
1.3.1	Visual Acceptance Criteria Tests	1	4.2.6	Test A1 - Pb-free Solder – Solder Bath/Dip and Look Test (Leads, Wires, etc.)	14
1.3.2	Force Measurement Tests	1	4.2.7	Test B1 - Pb-free Solder – Solder Bath/Dip and Look Test (Leadless Components)	15
1.4	Coating Durability	2	4.2.8	Test C1 - Pb-free Solder – Wrapped Wires Test (Lugs, Tabs, Terminals, Large Stranded Wires)	16
1.5	Solderability Backwards Compatibility	2	4.2.9	Test S1 - Pb-free Solder – Surface Mount Process Simulation Test	17
1.6	Referee Verification Solder Dip for Tests A, B, C, A1, B1, and C1	2	4.3	Force Measurement Tests	19
1.7	Limitations	2	4.3.1	Test E - SnPb Solder – Wetting Balance Solder Pot Test (Leaded Components)	19
1.8	Contractual Agreement	2	4.3.2	Test F - SnPb Solder – Wetting Balance	20
1.9	Terms and Definitions	2	4.3.3	Test G - SnPb Solder – Wetting Balance Globule Test	22
2	APPLICABLE DOCUMENTS	3	4.3.4	Test E1 - Pb-free Solder – Wetting Balance Solder Pot Test (Leaded Components)	24
2.1	Industry	3	4.3.5	Test F1 - Pb-free Solder – Wetting Balance Solder Pot Test (Leadless Components)	25
2.1.1	IPC	3	4.3.6	Test G1 - Pb-free Solder – Wetting Balance Globule Test	26
2.1.2	International Electrotechnical Commission	3	5	NOTES	27
2.2	Government	3	5.1	Use of Activated Flux	27
2.2.1	Federal	3	5.2	Massive Components	27
3	REQUIREMENTS	3	5.3	Sampling Plans	27
3.1	Materials	3	5.4	Correction for Buoyancy	27
3.1.1	Solder	3	5.5	Preconditioning Limitations	28
3.1.2	Flux	3	APPENDIX A	Critical Component Surfaces	29
3.1.3	Standard Copper Wrapping Wires	4	APPENDIX B	Evaluation Aids	38
3.1.4	Water	4	APPENDIX C	Calculation of Maximum Theoretical Force	43
3.2	Equipment	4	APPENDIX D	Calculation of Integrated Value of Area of the Wetting Curve	45
3.2.1	Steam Preconditioning Apparatus	4			
3.2.2	Bake Preconditioning Apparatus	4			
3.2.3	Optical Inspection Equipment	5			
3.2.4	Dipping Equipment	5			
3.2.5	Timing Equipment	5			
3.3	Preparation for Testing	5			
3.3.1	Specimen Preparation and Surface Condition	5			
3.3.2	Steam Conditioning	6			
3.3.3	Surfaces to be Tested	6			
3.4	Solder Bath Requirements	6			
3.4.1	Solder Contamination Control	6			
4	TEST PROCEDURES	7			
4.1	Application of Flux	7			
4.2	Visual Acceptance Criteria Tests	7			

APPENDIX E	Informative Annex	46	Figure A-10	Through-Hole Components - Round Pin	37
APPENDIX F	J-STD-002/J-STD-003 Activated Solderability Test Flux Rationale Committee Letter	47	Figure B-1	Defect Size Aid	38
APPENDIX G	Graphical Representations: Progression of Solder Wetting Curve Parameters As Measured By Wetting Balance Testing	49	Figure B-2	Types of Solderability Defects	39
			Figure B-3	Aids in Evaluation of 5% Allowable Area of Pin Holes	40
			Figure B-4	Aid in Evaluation of 5% Allowable Area of Pin Holes	41
APPENDIX H	Test Protocol for Wetting Balance Gauge Repeatability and Reproducibility (GR&R) Using Copper Foil Coupons	52	Figure B-5	Solderability Coverage Guide	42
			Figure C-1	Lead Periphery and Volume for a 132 I/O PQFP	43

Figures

Figure 3-1	Example Reticle	5
Figure 4-1	Dipping Schematic	8
Figure 4-2	Solder Dipping Angle for Surface Mount Leaded Components	8
Figure 4-3	Solder Dipping Depth for Through-Hole Components	9
Figure 4-4	Leadless Component Immersion Depth	10
Figure 4-5	Illustration of Acceptable Solderable Terminal	11
Figure 4-6	Illustration of Unsolderable Terminal	11
Figure 4-7	Illustration of Acceptable Solderable Stranded Wire	11
Figure 4-8	Illustration of Partially Solderable Stranded Wire Showing Incomplete Fillet	11
Figure 4-9	Wetting Balance Apparatus	19
Figure 4-10	Set A Wetting Curve	21
Figure 4-11	Set B Wetting Curve	21
Figure 4-12	Component and Dipping Angle (Directly from IEC 60068-2-69)	24
Figure A-1	“J” Leaded Components	29
Figure A-2	Passive Components	30
Figure A-3	Gull Wing Components	31
Figure A-4	Leadless Chip Carrier	32
Figure A-5	“L” Leaded Component	33
Figure A-6	Exposed Pad Package	34
Figure A-7	Bottom-Only Termination Component	34
Figure A-8	Area Array Component Critical Surface	35
Figure A-9	Through-Hole Components - Flat Pin	36

Tables

Table 3-1	Flux Compositions	4
Table 3-2	Steam Temperature Requirements	5
Table 3-3	Preconditioning Parameters for Solderability Testing	6
Table 3-4	Maximum Limits of Solder Bath Contaminant	7
Table 4-1	Test A Solderability Testing Parameters	8
Table 4-2	Test B Solderability Testing Parameters	10
Table 4-3	Test C Solderability Testing Parameters	11
Table 4-4	Test D Solderability Testing Parameters	13
Table 4-5	Stencil Thickness Requirements	13
Table 4-6	Reflow Parameter Requirements	14
Table 4-7	Test S Solderability Testing Parameters	14
Table 4-8	Test A1 Solderability Testing Parameters	15
Table 4-9	Test B1 Solderability Testing Parameters	16
Table 4-10	Test C1 Solderability Testing Parameters	17
Table 4-11	Stencil Thickness Requirements	18
Table 4-12	Pb-free Reflow Parameter Requirements	18
Table 4-13	Test S1 Solderability Testing Parameters	18
Table 4-14	Wetting Balance Parameter and Suggested Evaluation Criteria	20
Table 4-15	Dipping Angle and Immersion Depth for Components (Directly from IEC 60068-2-69)	23
Table 4-16	Wetting Parameters and Suggested Evaluation Criteria	24
Table 3-1	Flux Compositions	47

Solderability Tests for Component Leads, Terminations, Lugs, Terminals and Wires

1 PREFACE

1.1 Scope This standard prescribes test methods, defect definitions, acceptance criteria, and illustrations for assessing the solderability of electronic component leads, terminations, solid wires, stranded wires, lugs, and tabs. This standard also includes a test method for the resistance to dissolution/dewetting of metallization. This standard is intended for use by both vendor and user.

1.2 Purpose Solderability evaluations are made to verify that the solderability of component leads and terminations meets the requirements established in this standard and to determine that storage has had no adverse effect on the ability to solder components to an interconnecting substrate. Determination of solderability can be made at the time of manufacture, at receipt of the components by the user, or just before assembly and soldering.

The resistance to dissolution of metallization determination is made to verify that metallized terminations will remain intact throughout the assembly soldering processes.

In the case of a discrepancy, the description or written criteria always takes precedence over the illustrations.

1.2.1 Shall and Should The words “shall” or “shall not” are used in the text of this document wherever there is a requirement for materials, preparation, process control, or acceptance of a soldered connection or a test method. The word “should” reflects recommendations and is used to reflect general industry practices and procedures for guidance only.

Other documents to extent specified by the customer.

1.3 Method Classification This standard describes methods by which component leads or terminations may be evaluated for solderability. Any one of the following test methods - Test A, Test B, Test C, Test D, and Test S - may be used for SnPb solder processes and any one of the following test methods - Test A1, Test B1, Test C1, Test D, and Test S1 - may be used for Pb-free solder processes and are to be used for each application as a default unless otherwise AABUS.

1.3.1 Visual Acceptance Criteria Tests

Test A – Solder Bath/Dip and Look Test (Leaded Components and Stranded Wires) SnPb Solder (4.2.1)

Test B – Solder Bath/Dip and Look Test (Leadless Components) SnPb Solder (4.2.2)

Test C – Wrapped Wires Test (Lugs, Tabs, Hooked Leads, and Turrets) SnPb Solder (4.2.3)

Test D – Resistance to Dissolution/Dewetting of Metallization Test SnPb Solder and Pb-free Solder (4.2.4)

Test S – Surface Mount Process Simulation Test SnPb Solder (4.2.5)

Test A1 – Solder Bath/Dip and Look Test (Leaded Components and Stranded Wires) Pb-free Solder (4.2.6)

Test B1 – Solder Bath/Dip and Look Test (Leadless Components) Pb-free Solder (4.2.7)

Test C1 – Wrapped Wires Test (Lugs, Tabs, Hooked Leads, and Turrets) Pb-free Solder (4.2.8)

Test S1 – Surface Mount Process Simulation Test Pb-free Solder (4.2.9)

1.3.2 Force Measurement Tests

Test E – Wetting Balance Solder Pot Test (Leaded Components) SnPb Solder (4.3.1)

Test F – Wetting Balance Solder Pot Test (Leadless Components) SnPb Solder (4.3.2)

Test G – Wetting Balance Globule Test SnPb Solder (4.3.3)

Test E1 – Wetting Balance Solder Pot Test (Leaded Components) Pb-free Solder (4.3.4)

Test F1 – Wetting Balance Solder Pot Test (Leadless Components) Pb-free Solder (4.3.5)

Test G1 – Wetting Balance Globule Test Pb-free Solder (4.3.6)